

GL Silicon N-Channel Power MOSFET

General Description:

The GL1130-8 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is SOP-8, which accords with the RoHS standard.

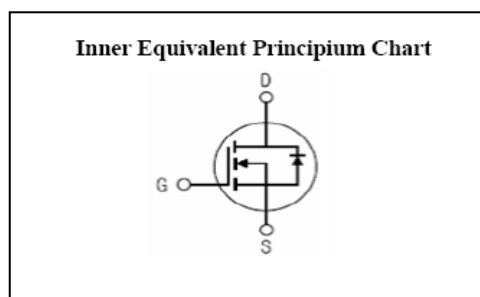
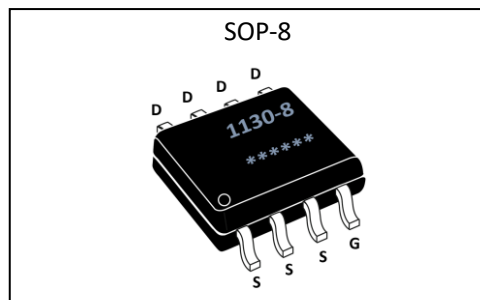
Features:

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications:

- PWM applications
- Load switch
- Power management

V_{DSS}	30	V
I_D	8	A
P_D	2.5	W
$R_{DS(ON)MAX}$	20	mΩ



Absolute (Tc=25°C unless otherwise specified):

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	30	V
I_D	Continuous Drain Current	8	A
	Continuous Drain Current $T_C = 70\text{ }^{\circ}\text{C}$	6	A
I_{DM}^{a1}	Pulsed Drain Current	32	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{as}^{a2}	$L=0.1\text{mH}$	28	mJ
dv/dt^{a3}	Peak Diode Recovery dv/dt	5.0	V/ns
P_D	Power Dissipation	2.5	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^{\circ}\text{C}$
T_L	Maximum Temperature for Soldering	300	$^{\circ}\text{C}$

**GL Silicon N-Channel Power MOSFET****Electrical Characteristics** (Tc=25°C unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	30	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=-250\mu A$, Reference 25°C	--	0.1	--	V/°C
I_{DSS}	Drain to Source Leakage Current	$V_{DS}=30V, V_{GS}=0V, T_a=25^\circ C$	--	--	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_a=125^\circ C$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+20V$	--	--	1	μA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-20V$	--	--	-1	μA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=5A$	--	11	20	mΩ
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=4.5V, I_D=5.0A$	--	15	26	mΩ
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	--	1.5	V
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=10A$	15	--	--	S
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=15V$ $f=1.0MHz$	--	680	--	pF
C_{oss}	Output Capacitance		--	160	--	
C_{rss}	Reverse Transfer Capacitance		--	80	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=1A, V_{DD}=25V$ $V_{GS}=10V, R_G=6\Omega$	--	13	--	ns
t_r	Rise Time		--	8	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	40	--	
t_f	Fall Time		--	30	--	
Q_g	Total Gate Charge	$I_D=5A, V_{DD}=30V$ $V_{GS}=5V$	--	8	--	nC
Q_{gs}	Gate to Source Charge		--	4.8	--	
Q_{gd}	Gate to Drain ("Miller") Charge		--	2.2	--	

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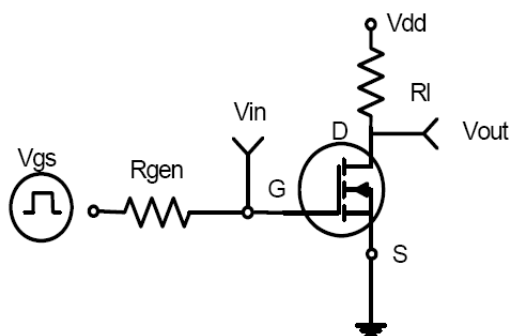
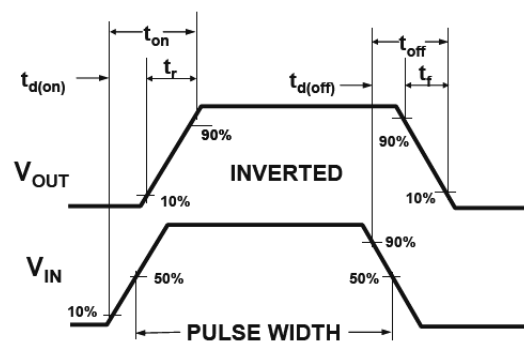
Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)		--	--	8	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	32	A
V_{SD}	Diode Forward Voltage	$I_S=8A, V_{GS}=0V$	--	--	1.5	V
t_{rr}	Reverse Recovery Time	$I_S=8A, T_J=25^{\circ}C$	--	60	--	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt=100A/us, V_{GS}=0V$	--	150	--	nC
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

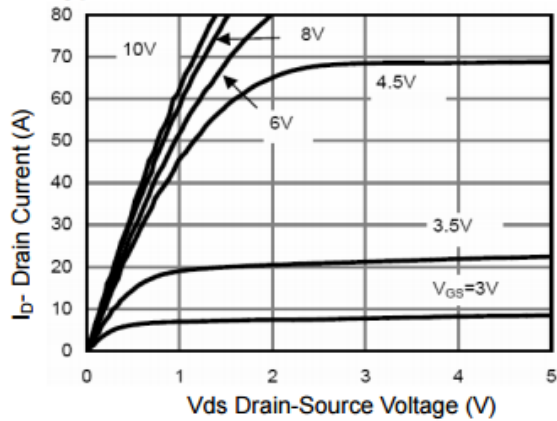
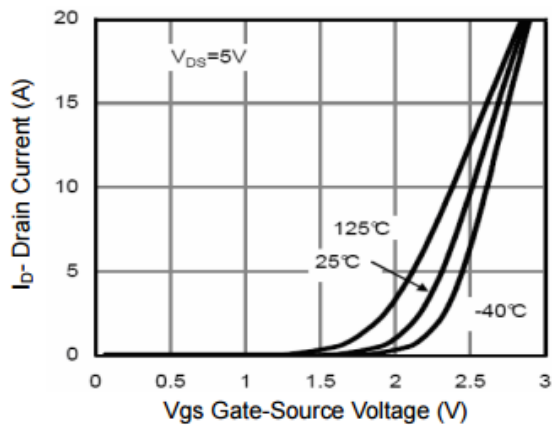
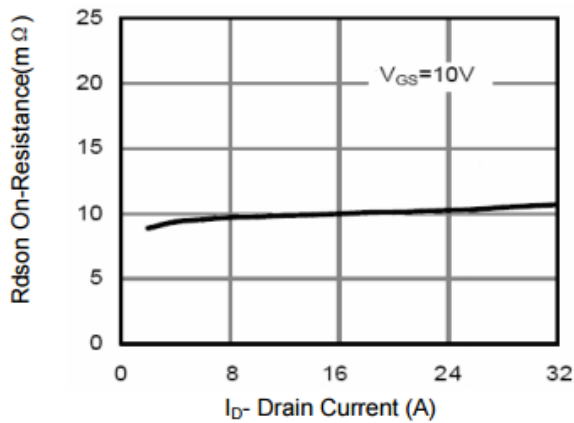
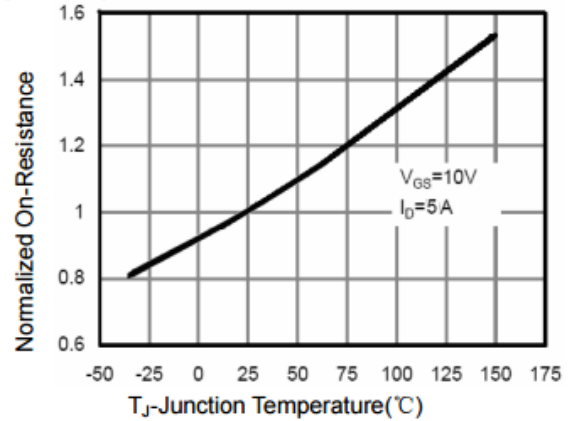
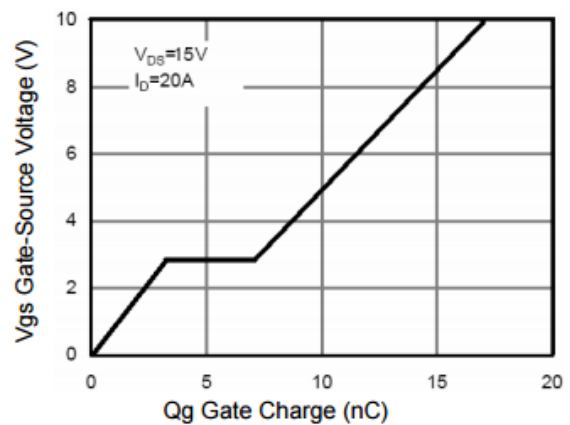
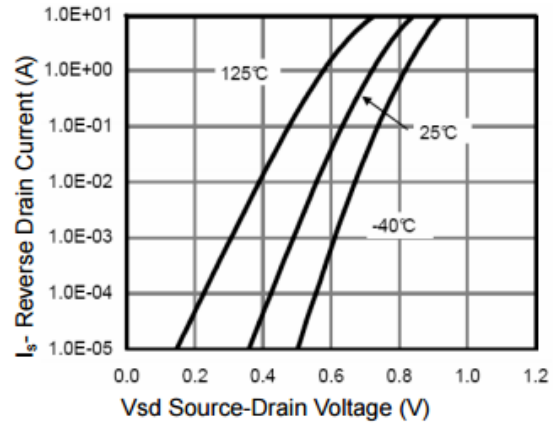
Symbol	Parameter	Typ.	Units
$R_{\theta JA}$	Junction-to-Ambient	50	$^{\circ}C/W$

a1: Repetitive rating; pulse width limited by maximum junction temperature

a2: $T_J=25^{\circ}C, V_{DD}=15V, V_G=10V, L=0.1mH$

a3: $I_{SD}=8A, di/dt \leq 100A/us, V_{DD} \leq BV_{DS}, \text{Start } T_J=25^{\circ}C$

Typical Electrical and Thermal Characteristics

Figure 1: Switching Test Circuit

Figure 2: Switching Waveforms

Typical Electrical and Thermal Characteristics (Curves)

Figure 1 Output Characteristics

Figure 2 Transfer Characteristics

Figure 3 Rdson- Drain Current

Figure 4 Rdson-Junction Temperature

Figure 5 Gate Charge

Figure 6 Source- Drain Diode Forward

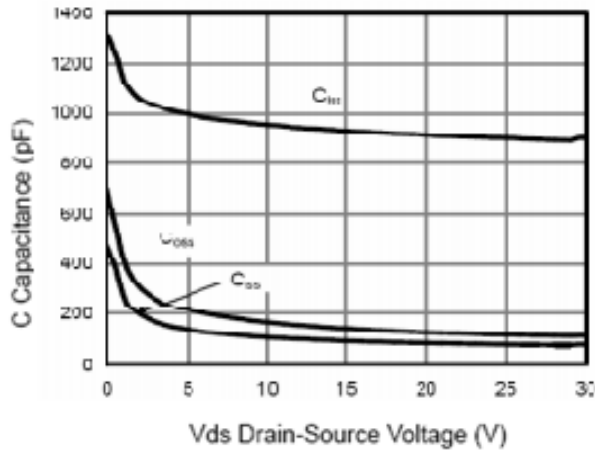


Figure 7 Capacitance vs Vds

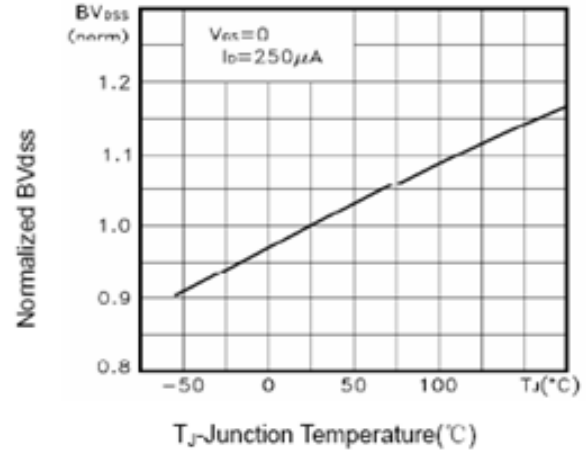


Figure 9 BV_{DSS} vs Junction Temperature

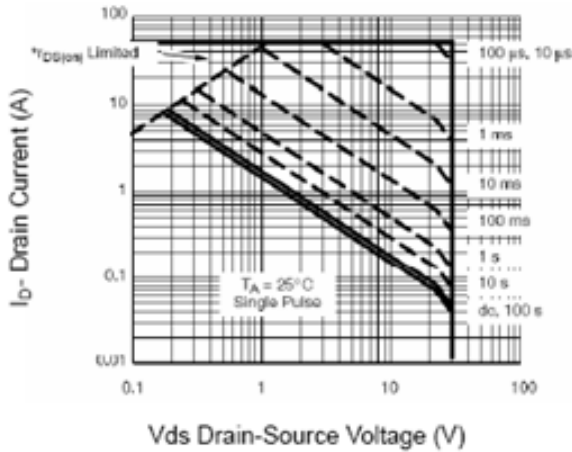


Figure 8 Safe Operation Area

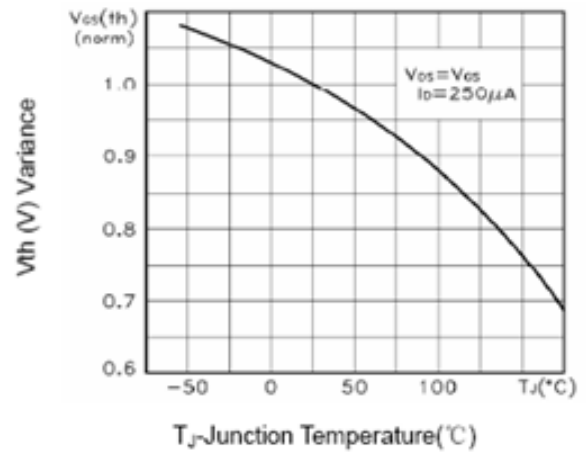


Figure 10 $V_{GS(th)}$ vs Junction Temperature

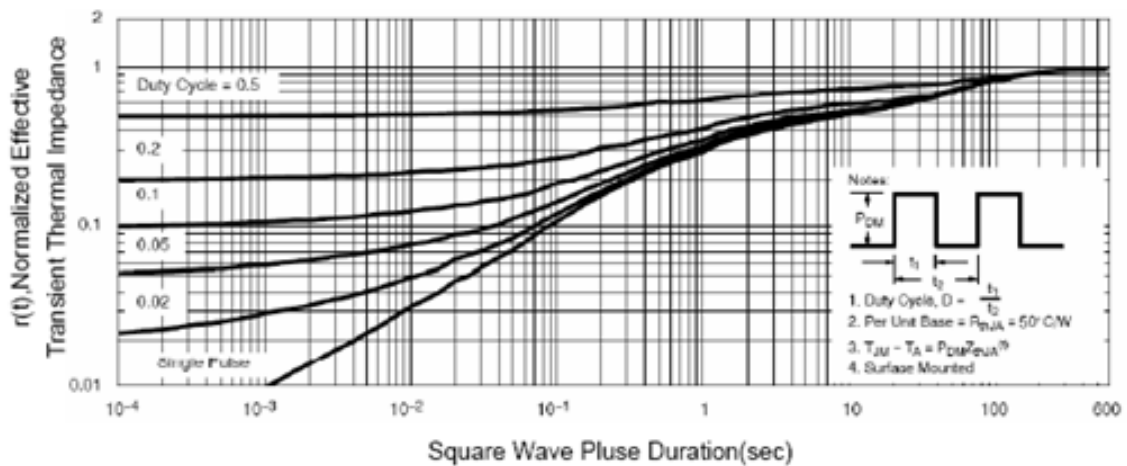


Figure 11 Normalized Maximum Transient Thermal Impedance

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